

ESD11A3.3DT5G SERIES

ESD Protection Diode

Ultra Small SOT-1123 Package

The ESD11A Series is designed to protect voltage sensitive components from damage due to ESD. These parts provide excellent ESD clamping capability and fast response time to enhance the immunity of the end application from system level ESD stress such as IEC61000-4-2. Two uni-directional surge protection diodes are housed in the ultra small SOT-1123 package, making these parts ideal for ESD protection on designs where board space is at a premium, such as cell phones, MP3 players and many other portable handheld electronic devices.

Specification Features:

- Low Clamping Voltage
- Small Body Outline Dimensions:
0.039" x 0.024" (1.0 mm x 0.6 mm)
- Low Body Height: 0.016" (0.4 mm)
- Stand-off Voltage: 3.3 V – 5 V
- Low Leakage
- Response Time is Typically < 1 ns
- IEC61000-4-2 Level 4 ESD Protection
- AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic
Epoxy Meets UL 94 V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

QUALIFIED MAX REFLOW TEMPERATURE: 260°C

Device Meets MSL 1 Requirements

Table 1. MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Contact		±15	kV
Total Power Dissipation on FR-5 Board (Note 1) @ T _A = 25°C	P _D	150	mW
Storage Temperature Range	T _{stg}	-55 to +150	°C
Junction Temperature Range	T _J	-55 to +125	°C
Lead Solder Temperature – Maximum (10 Second Duration)	T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

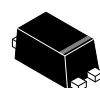
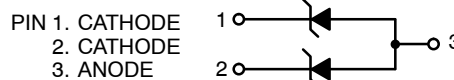
1. FR-5 = 1.0 x 0.75 x 0.62 in.

See Application Note AND8308/D for further description of ESD maximum ratings.



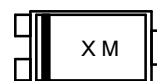
ON Semiconductor®

www.onsemi.com



**SOT-1123
CASE 524AA**

MARKING DIAGRAM



X = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
ESD11AxxDT5G	SOT-1123 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

ESD11A3.3DT5G SERIES

Table 2. ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F
P_{pk}	Peak Power Dissipation
C	Capacitance @ $V_R = 0$ and $f = 1$ MHz

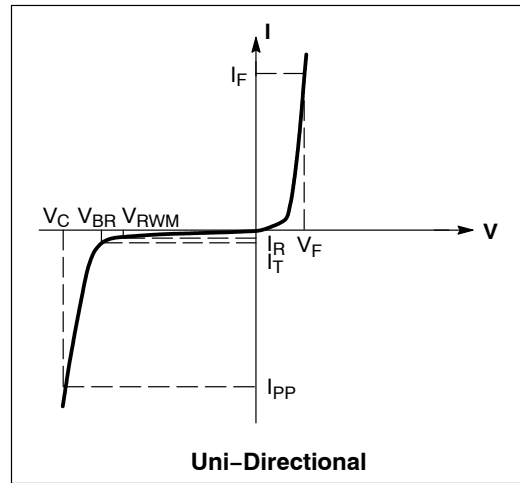


Table 3. ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.9$ V Max. @ $I_F = 10$ mA for all types)

Device	Device Marking	V_{RWM} (V)	I_R (μA) @ V_{RWM}	V_{BR} (V) @ I_T (Note 2)	I_T (mA)	C (pF), uni-directional (Note 3)		V_C (V) @ $I_{PP} = 1$ A (Note 5)	V_C (V) IEC61000-4-2 (Note 6)
		Max	Max	Min		Typ	Max	Max	Typ
ESD11A3.3DT5G	2*	3.3	1.0	5.2	1.0	25	35	7.8	Figures 1 thru 4
ESD11A5.0DT5G	3*	5.0	0.1	6.2	1.0	20	30	9.5	Figures 1 thru 4

*Rotated 90° clockwise.

2. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C .

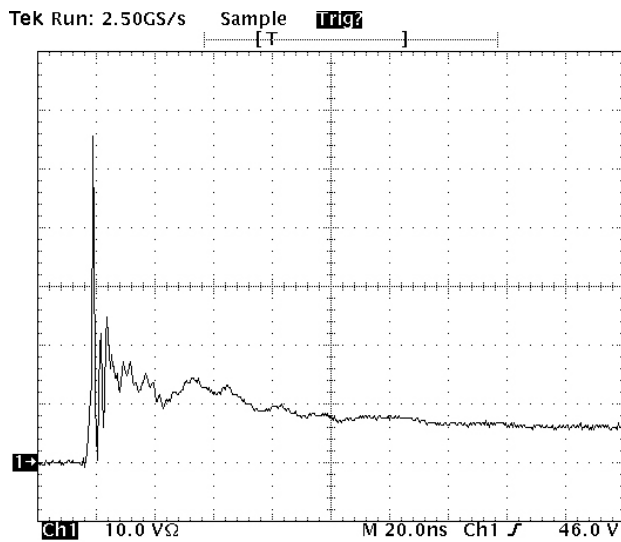
3. Uni-directional capacitance at $f = 1$ MHz, $V_R = 0$ V, $T_A = 25^\circ\text{C}$ (pin1 to pin 3; pin 2 to pin 3).

4. Bi-directional capacitance at $f = 1$ MHz, $V_R = 0$ V, $T_A = 25^\circ\text{C}$ (pin1 to pin 2).

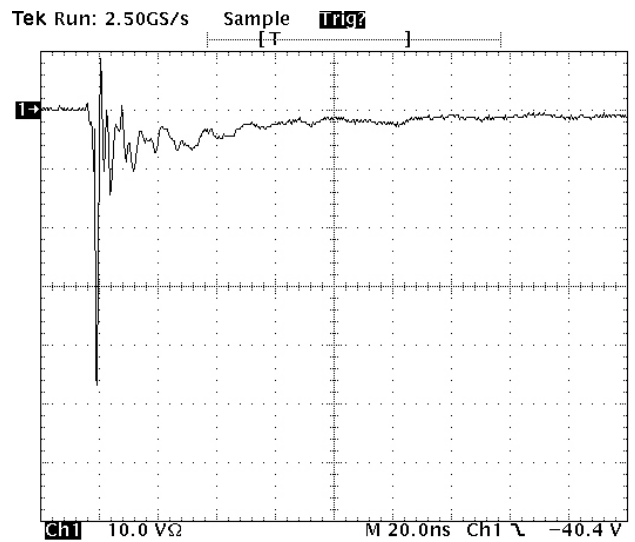
5. Surge current waveform per Figure 7.

6. Typical waveform. For test procedure see Figures 5 and 6 and Application Note AND8307/D.

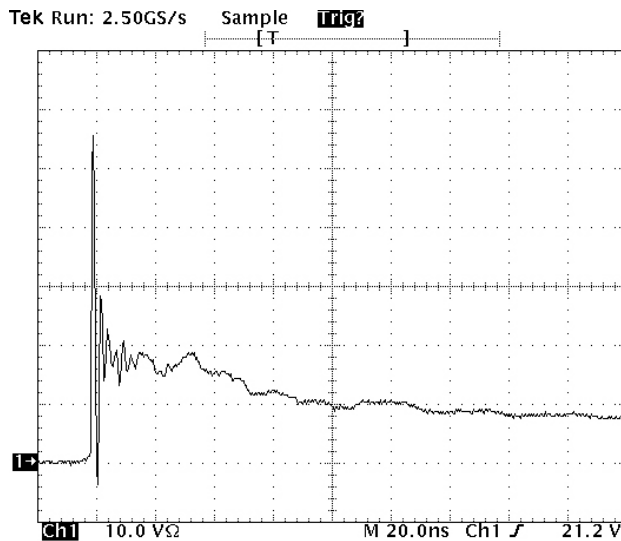
ESD11A3.3DT5G SERIES



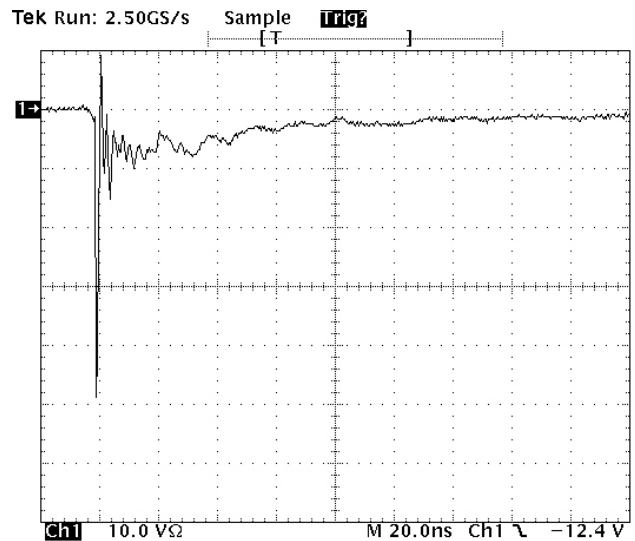
**Figure 1. ESD11A3.3D Clamping Voltage Screenshot
Positive 8 kV contact per IEC 61000-4-2**



**Figure 2. ESD11A3.3D Clamping Voltage Screenshot
Negative 8 kV contact per IEC 61000-4-2**



**Figure 3. ESD11A5.0D Clamping Voltage Screenshot
Positive 8 kV contact per IEC 61000-4-2**



**Figure 4. ESD11A5.0D Clamping Voltage Screenshot
Negative 8 kV contact per IEC 61000-4-2**

ESD11A3.3DT5G SERIES

IEC 61000-4-2 Spec.

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

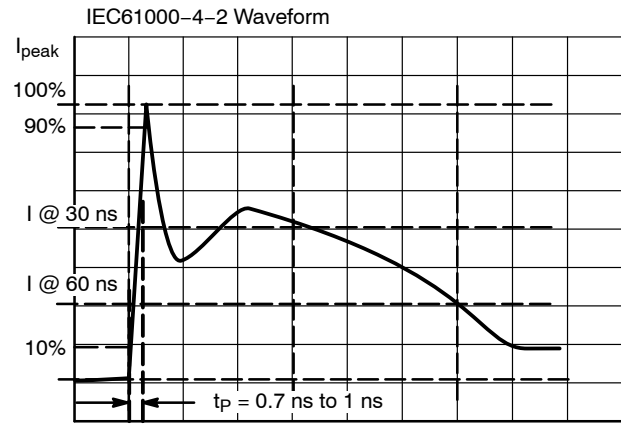


Figure 5. IEC61000-4-2 Spec

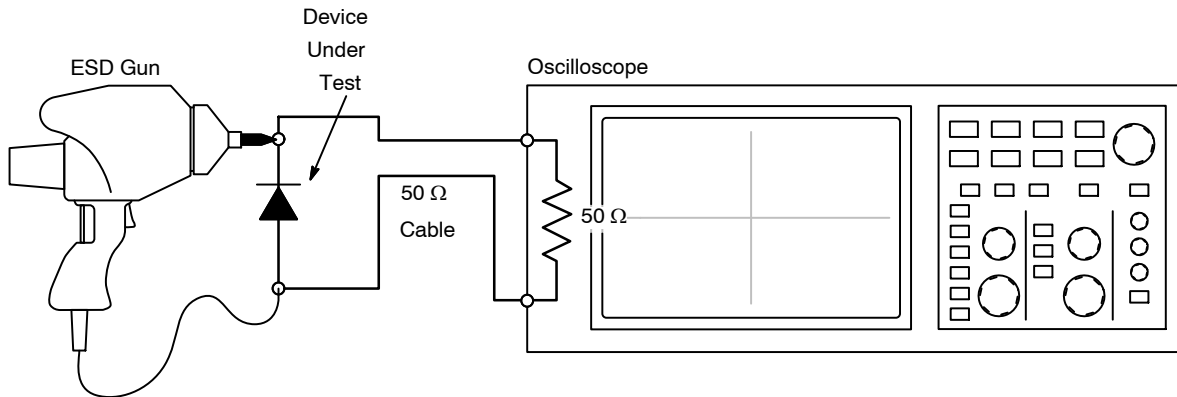


Figure 6. Diagram of ESD Test Setup

The following is taken from Application Note AND8308/D – Interpretation of Datasheet Parameters for ESD Devices.

ESD Voltage Clamping

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000-4-2 waveform. Since the IEC61000-4-2 was written as a pass/fail spec for larger

systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

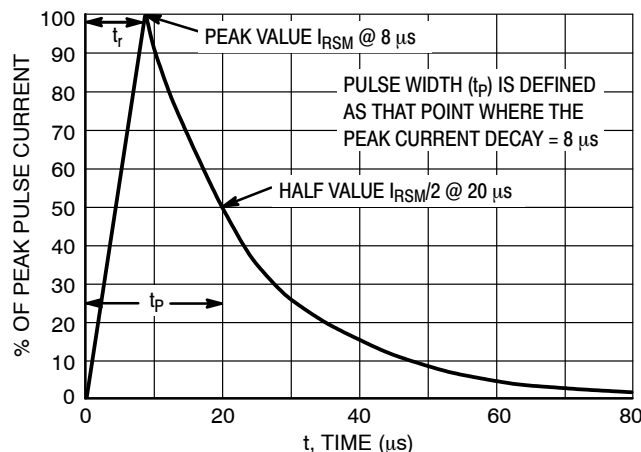
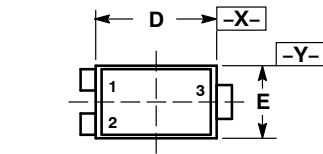


Figure 7. 8 X 20 μ s Pulse Waveform

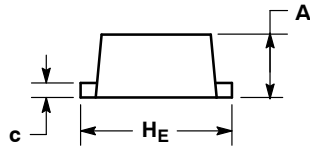
ESD11A3.3DT5G SERIES

PACKAGE DIMENSIONS

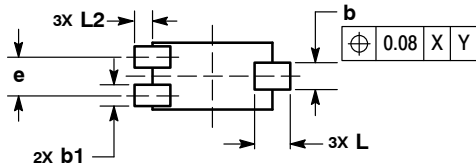
SOT-1123
CASE 524AA
ISSUE C



TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTES:

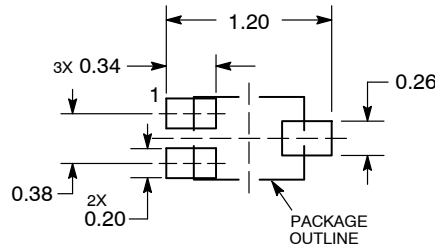
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE

BURRS		
MILLIMETERS		
DIM	MIN	MAX
A	0.34	0.40
b	0.15	0.28
b1	0.10	0.20
c	0.07	0.17
D	0.75	0.85
E	0.55	0.65
e	0.35	0.40
H _E	0.95	1.05
L	0.185	REF
L2	0.05	0.15

STYLE 4:


1. CATHODE
2. CATHODE
3. ANODE

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marketing.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[ON Semiconductor:](#)

[ESD11A5.0DT5G](#)